## 504302080 04/01/2017

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
HAOXIANG DONG	02/24/2017

#### **RECEIVING PARTY DATA**

Name:	SHENZHEN HUIDING TECHNOLOGY CO., LTD.	
Street Address:	FLOOR 13, PHASE B, TENGFEI INDUSTRIAL BUILDING	
Internal Address:	FUTIAN FREE TRADE ZONE	
City:	SHENZHEN	
State/Country:	CHINA	
Postal Code:	518000	

# **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	15477084

#### **CORRESPONDENCE DATA**

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 469-450-9878
Email: admin@firstipr.com

Correspondent Name: FIRSTIPR

Address Line 1: 7540 WRIGHT DR.
Address Line 4: FRISCO, TEXAS 75035

ATTORNEY DOCKET NUMBER:	LSLD-PI8052WDUS	
NAME OF SUBMITTER:	WEI WANG	
SIGNATURE:	/Wei Wang/	
DATE SIGNED:	04/01/2017	

**Total Attachments: 2** 

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PATENT REEL: 041819 FRAME: 0457

504302080

Docketing No.: LSLD-PI8052WDUS

#### ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged,

ASSIGNOR:

#### Haoxiang DONG

c/o Floor 13, Phase B, Tengfei Industrial Building, Futian Free Trade Zone, Shenzhen, Guangdong 518000, P.R. China

hereby sells, assigns and transfers to

ASSIGNEE:

### SHENZHEN HUIDING TECHNOLOGY CO., LTD.

Floor 13, Phase B, Tengfei Industrial Building, Futian Free Trade Zone, Shenzhen, Guangdong 518000, P.R. China

and the successors, assigns and legal representatives of the ASSIGNEE the entire rights, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the Application entitled:

# PACKAGE STRUCTURE, ELECTRONIC DEVICE AND METHOD FOR MANUFACTURING PACKAGE STRUCTURE

which application was executed by the undersigned on even date herewith

and, in and to all Letters patent to be obtained for said invention by the above application on any continuation, divisional, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known as accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

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IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

Harxiony Donz

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